



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN MPA-MIC/06/2150
Notification Date 11/03/2006

Second Source for uPSD Assembly

MIC - MICROCONTROLLERS

Table 1. Change Identification

Product Identification (Product Family/Commercial Product)	All uPSD Products
Type of change	Package assembly location change
Reason for change	Increased product demand, and flexibility in manufacturing
Description of the change	STATSCHIPPAC Singapore will be qualified as a second source for assembly of all uPSD products.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Trace code on part marketing (details attached)
Manufacturing Location(s)	

Table 2. Change Implementation Schedule

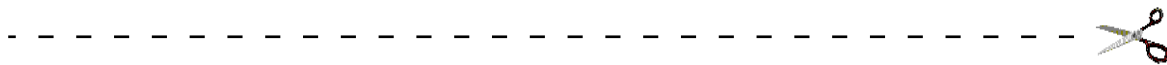
Forecasted implementation date for change	24-Feb-2007
Forecasted availability date of samples for customer	07-Apr-2007
Forecasted date for STMicroelectronics change Qualification Plan results availability	12-Jan-2007
Estimated date of changed product first shipment	07-Apr-2007

Table 3. Change Responsibility

	Name	Signature	Date
Division Product Manager	Steve Cheng		Nov.01 ,06
Division Q.A. Manager	Manooch Golabi		Nov.01 ,06
Division Marketing Manager	Bryan Hahn		Nov.01 ,06

Table 4. List of Attachments

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt		PCN MPA-MIC/06/2150
Please sign and return to STMicroelectronics Sales Office		Notification Date 11/03/2006
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	Name:	
	Title:	
	Company:	
	Date:	
	Signature:	
Remark		



Quality Bulletin

Date: November 1, 2006

Second Source for uPSD Assembly

FROM:

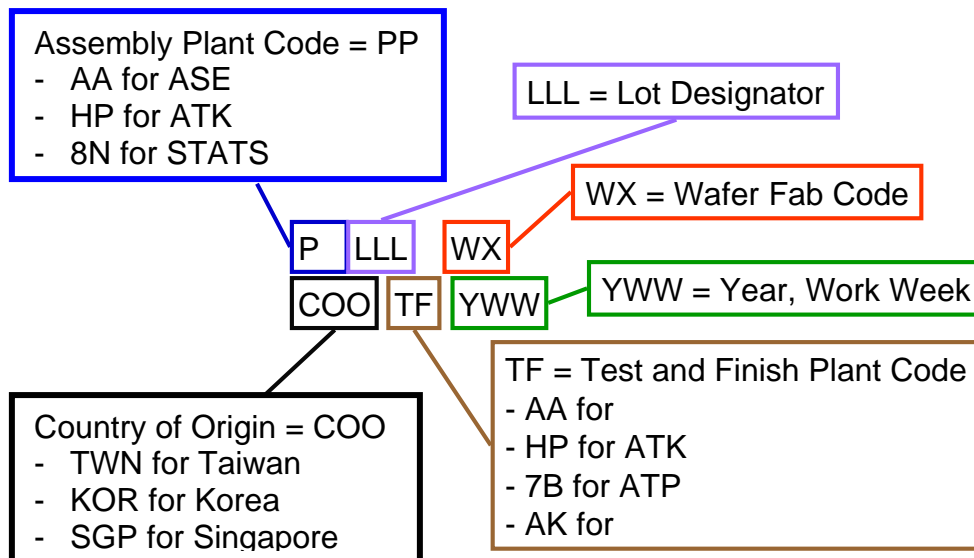
Bryan Hahn
Product Marketing Manager
Ph (408) 467 8470
Fax (408) 452 7718
Email: bryan.hahn@st.com

Re: Additional Manufacturing Capability

The uPSD family of microcontrollers is continuing to gain industry acceptance and increased use in numerous and varied products.

To meet the increased product demand, and to enable flexibility for the, ST is announcing the addition of STATSCHIPPAC Singapore (STATS) as a second assembly source for uPSD products.

Future products may be assembled at the current assembly plant Amkor Technologies, Korea (ATK) or at STATS. Products may be tested at either ATK or KYEC Taiwan. Assembly and Test location information is included in the part marking as outlined below:



Assembly qualification is scheduled to be completed December 31st, 2006 with Production release the week of February 19th, 2007.

Quality Bulletin

If there are any questions concerning this issue, or any other questions I can help to answer, please feel free to contact me by phone at 408 467 8470, or by email at bryan.hahn@st.com.

Sincerely,

Bryan Hahn
Product Marketing Manager
MCD Division
STMicroelectronics

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